

Variant: 001  
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 TID #: PMP15040



**PMP15040 REV E1 Bill of Materials**

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	IPCB1	1		BSR019	Any	Printed Circuit Board	
2	C1	1	100uF	GRM32ER60J107ME20L	MuRata	CAP, CERM, 100 µF, 6.3 V, +/- 20%, X5R, 1210	1210
3	C2	1	4.7uF	CGA6M3X7S2A475K200AB	TDK	CAP, CERM, 4.7 µF, 100 V, +/- 10%, X7S, AEC-Q200 Grade 1, 1210	1210
4	C3, C4	2	0.047uF	CGA3E3X7S2A473K080AB	TDK	CAP, CERM, 0.047 µF, 100 V, +/- 10%, X7S, AEC-Q200 Grade 1, 0603	0603
5	C5	1	0.1uF	GRM155R71E104KE14D	MuRata	CAP, CERM, 0.1 uF, 25 V, +/- 10%, X7R, 0402	0402
6	C6	1	1uF	C1005X7S1A105K050BC	TDK	CAP, CERM, 1 uF, 10 V, +/- 10%, X7S, 0402	0402
7	L1	1	18uH	LPS4018-183MLB	Coilcraft	Inductor, Shielded Drum Core, Ferrite, 18 uH, 0.85 A, 0.27 ohm, SMD	LPS4018
8	R1, R2	2	100k	CRCW0402100KFKED	Vishay-Dale	RES, 100 k, 1%, 0.063 W, 0402	0402
9	R3	1	24.9k	CRCW040224K9FKED	Vishay-Dale	RES, 24.9 k, 1%, 0.063 W, 0402	0402
10	TP1, TP2, TP3	3		5015	Keystone	Test Point, Miniature, SMT	Testpoint_Keystone_Miniature
11	U1	1		LMR36006BRNXR	Texas Instruments	65-V 0.6-A Synchronous Step-Down Converter, RNX0012B (VQFN-HR-12)	RNX0012B
12	ZZ1	1				This Assembly Note is for PCB labels only	

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